

UNISONIC TECHNOLOGIES CO., LTD

MGBR10U300

MOS GATED BARRIER RECTIFIER

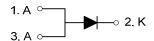
■ DESCRIPTION

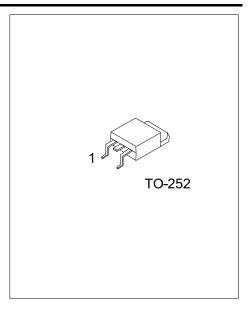
The UTC **MGBR10U300** is a surface mount mos gatedbarrier rectifier,it uses UTC's advanced technology to provide customers withlow forward voltage drop and high switching speed, etc.

■ FEATURES

- * Ultra low forward voltage drop
- * High switching speed

■ SYMBOL

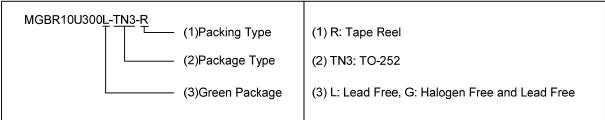




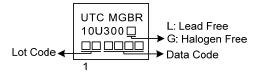
■ ORDERING INFORMATION

Ordering Number		Dookogo	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
MGBR10U300L-TN3-R	MGBR10U300G-TN3-R	TO-252	Α	K	Α	Tape Reel	

Note: Pin Assignment: A: Anode K: Common Cathode



■ MARKING



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MGBR10U300 DIODE

■ ABSOLUTE MAXIMUM RATINGS (T_A=25°C, unless otherwise specified)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

PARAMETER	SYMBOL	RATINGS	UNIT
DC Blocking Voltage	V_{RM}	300	V
Working Peak Reverse Voltage	V_{RWM}	300	V
Peak Repetitive Reverse Voltage	V _{RRM} 300		V
Average Rectified Output Current T _C =140°C	Ιο	10	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	160	Α
Operating Junction Temperature	TJ	-65~+150	Ŝ
Storage Temperature	T _{STG}	-65~+150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■ THERMAL CHARACTERISTICS (Note 3)

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	110	°C/W
Junction to Case	θ_{JC}	6	°C/W

■ ELECTRICAL CHARACTERISTICS (T_A=25°C,unless otherwise specified.)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Reverse Breakdown Voltage (Note 1)	$V_{(BR)R}$	I _R =0.5mA	300			V
Forward Voltage Drop	V _{FM}	I _F =10A, T _J =25°C			0.85	V
		I _F =10A, T _J =125°C			0.75	V
Leakage Current (Note 1)	I _{RM}	V _R =300V, T _J =25°C			100	μΑ
		V _R =300V, T _J =125°C			10	mA

Notes: 1. Short duration pulse test used to minimize self-heating effect.

- 2. Thermal resistance junction to case mounted on heatsink.
- 3. Mounted on an FR4 PCB, single-sided copper, with 100 cm² copper pad area.

MGBR10U300 DIODE

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